# **Technical Data Sheet**

# 1206 Package Chip LED(0.8nm Height)

#### Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version

### Descriptions

- The 1206 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packingdensity, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

### Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

### **Device Selection Guide**

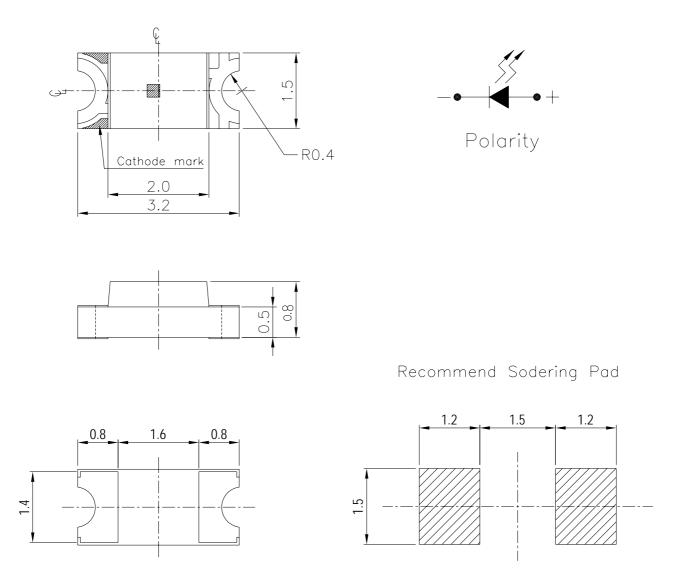
Bort NO	Chip	Emitted Color	Resin Color	
Part NO.	Material	Emitted Color		
KO-1206QRC/08	AlGaInP	Brilliant Red	Water Clear	



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### **Package Outline Dimensions**



**Note:** Tolerances Unless Dimension is  $\pm 0.1$ mm, Unit = mm

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### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V <sub>R</sub>	5	V	
Forward Current	$I_{\rm F}$	25	mA	
Peak Forward Current (Duty 1/10 @1KHz)	$I_{FP}$	60	mA	
Power Dissipation	Pd	60	mW	
Electrostatic Discharge(HBM)	ESD	2000	V	
Operating Temperature	Topr	-40 ~ +85	°C	
Storage Temperature	Tstg	-40~ +90	°C	
Soldering Temperature	Tsol	Reflow Soldering:260 °C for 10 sec Hand Soldering:350°C for 3 sec		

### Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	72.0		140	mcd	
Viewing Angle	2 <del>0</del> 1/2		130		deg	
Peak Wavelength	λp		632		nm	
Dominant Wavelength	λd	621		631	nm	I <sub>F</sub> =20mA
Spectrum Radiation Bandwidth	$ riangle \lambda$		20		nm	
Forward Voltage	VF	1.75		2.35	V	
Reverse Current	IR			10	$\mu A$	V <sub>R</sub> =5V

#### Notes:

1.Tolerance of Luminous Intensity ±11%

#### 2.Tolerance of Dominant Wavelength ±1nm

3.Tolerance of Forward Voltage ±0.1V

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#### **Bin Range Of Dom. Wavelength**

Group	Bin	Min	Max	Unit	Condition
F	FF1	621	626		1 20 4
	FF2	626	631	nm	I <sub>F</sub> =20mA

#### **Bin Range Of Luminous Intensity**

Bin	Min	Max	Unit	Condition
Q1	72.0	90.0		
Q2	90.0	112	mcd	I <sub>F</sub> =20mA
R1	112	140		

#### **Bin Range Of Luminous Voltage**

Group	Bin	Min	Max	Unit	Condition	
В	0	1.75	1.95			
	1	1.95	2.15	V	I <sub>F</sub> =20mA	
	2	2.15	2.35			

#### Notes:

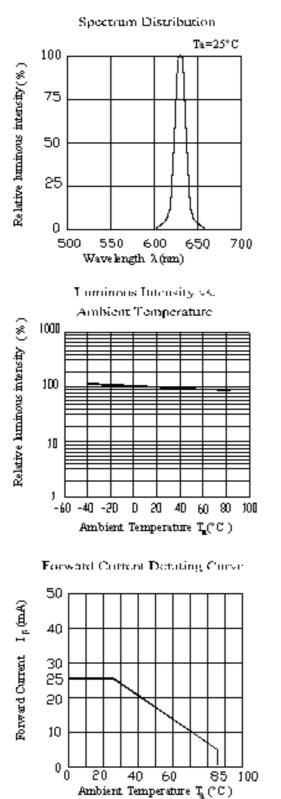
1.Tolerance of Luminous Intensity ±11%

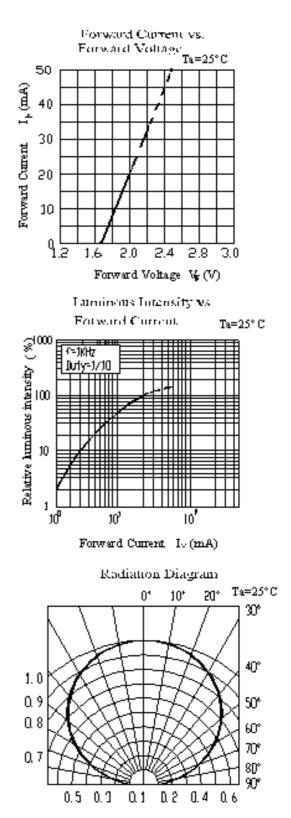
2.Tolerance of Dominant Wavelength ±1nm

3.Tolerance of Forward Voltage ±0.1V

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## **Typical Electro-Optical Characteristics**





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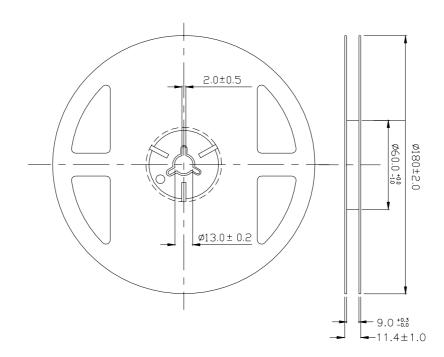
#### Label explanation

**CAT: Luminous Intensity Rank** 

HUE: Dom. Wavelength Rank

**REF: Forward Voltage Rank** 

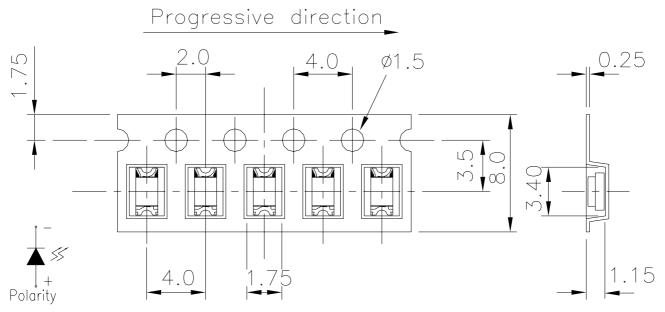
## **Reel Dimensions**



**Note:** The tolerances unless mentioned is  $\pm 0.1$  mm ,Unit = mm

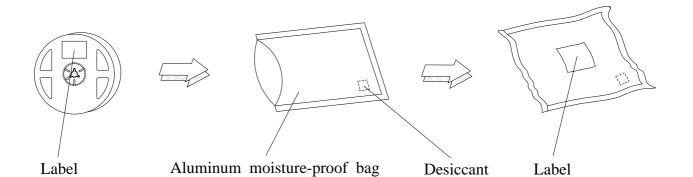
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### **Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel**



**Note:** Tolerances Unless Dimension is  $\pm 0.1$  mm , Unit = mm

### **Moisture Resistant Packaging**



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## **Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below. Confidence level : 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C ±5°C Min.5 sec.	6 Min.	22 Pcs.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H: +100°C 5min $\int 10 \sec$ L: -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	<b>Temp.</b> : -40°℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C/85%RH	1000 Hrs.	22 PCS.	0/1

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### **Precautions For Use**

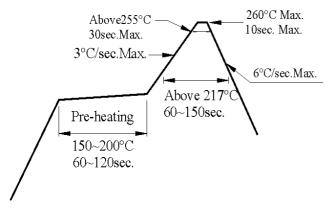
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).

- 2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package: The LEDs should be kept at  $30^{\circ}$ C or less and 90% RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30  $^\circ\!C$   $\,$  or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
  Baking treatment : 60±5°C for 24 hours.
- 3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

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#### 4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

